Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **QA**
2. **QA**
3. **CA**
4. **RA**
5. **KA**
6. **JA**
7. **SA**
8. **VSS**
9. **SB**
10. **JB**
11. **KB**
12. **RB**
13. **CB**
14. **QB**
15. **QB**
16. **GND**

**.052”**

**6 5 4**

**7**

**8**

**9**

**10**

**11**

**3**

**2**

**1**

**16**

**15**

**14**

**12 13**

**.059”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004 x .004”**

**Backside Potential:**

**Mask Ref: MC14027B**

**APPROVED BY: DK DIE SIZE .052” X .059” DATE: 6/8/21**

**MFG: MOTOROLA THICKNESS .014” P/N: MCC14027B**

**DG 10.1.2**

#### Rev B, 7/1